IN THE CLAIMS:

Please cancel claims 1, 6, 7, 9, 11, 13, 15, 16, 18, 20, 21, 22, 24, 26-29, 31, 34, 35, 37, and 39-43 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claims 2, 3, 4, 5, and 32, and add new claim 45 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Canceled)

2. (Currently Amended) ~~The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1,~~A heat conductivity and brightness enhancing structure for light-emitting diode comprising: a bracket having:

a) a cathode leg support;

b) a bowl formed in an upper end of the cathode leg support;

c) a light-emitting chip located in the bowl; and

d) at least one depression formed in a bottommost section of the bowl and receiving an adhesive therein, the at least one depression having an opening directed toward the chip, the opening having a diameter smaller than a bottom face of the chip, the adhesive filling the at least one depression and adhering the chip in the bowl.

~~wherein a column hole is formed through the cathode leg support from at least one depression of the bowl to outer side of the bracket.~~

3. (Currently Amended) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim ~~1~~ 32, wherein a column blind hole is formed in the cathode leg support from a portion below at least one depression of the bowl by a certain thickness to an outer side of the leg support.

4. (Currently Amended) ~~The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1,~~A heat conductivity and brightness enhancing structure for light-emitting diode comprising: a bracket having:

a) a cathode leg support;

b) a bowl formed in an upper end of the cathode leg support;

c) a light-emitting chip located in the bowl; and

d) at least one depression formed in a bottommost section of the bowl and receiving an adhesive therein, the at least one depression having an opening directed toward the chip, the opening having a diameter smaller than a bottom face of the chip, the adhesive filling the at least one depression and adhering the chip in the bowl,

wherein the bowl ~~is formed of at least one stage of~~ has a recessed face having at least two steps.

5. (Currently Amended) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the ~~is formed of at least one stage of~~ has a recessed face having at least one step.

Claims 6-7. (Canceled)

8. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the circumference of the depression of the bowl is formed with concentric recesses.

Claim 9. (Canceled)

10. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein the circumference of the depression of the bowl is formed with concentric recesses.

Claim 11. (Canceled)

12. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.

Claim 13. (Canceled)

14. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.

Claims 15-16. (Canceled)

17. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.

Claim 18. (Canceled)

19. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.

Claims 20-22. (Canceled)

23. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.

Claim 24. (Canceled)

25. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.

Claims 26-29. (Canceled)

30. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 23, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board and partially suspended.

Claim 31. (Canceled)

32. (Currently Amended) ~~The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 22,~~ A heat conductivity and brightness enhancing structure for light-emitting diode comprising: a bracket having:

a) a cathode leg support;

b) a bowl formed in an upper end of the cathode leg support;

c) a light-emitting chip located in the bowl; and

d) at least one depression formed in a bottommost section of the bowl and receiving an adhesive therein, the at least one depression having an opening directed toward the chip, the opening having a diameter smaller than a bottom face of the chip, the adhesive filling the at least one depression and adhering the chip in the bowl,

wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board,

wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.

33. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 23, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.

Claims 34-35. (Canceled)

36. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

Claim 37. (Canceled)

38. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

Claims 39-43. (Canceled)

44. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 32, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

45. (New) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein a column hole is formed through the cathode leg support from at least one depression of the bowl to an outer side of the bracket.